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## 1. Absolute Maximum Ratings

Current polarities are defined as follows: current going into the IC (sinking) is positive current (+); and current coming out of the IC (sourcing) is negative current (–).

Unless otherwise specified,  $T_A = 25\text{ }^{\circ}\text{C}$ .

Characteristic	Symbol	Conditions	Pin	Rating	Units
VSEN Pin Voltage	$V_{SEN}$		1 – 4	– 0.3 to $V_{REG}$	V
VCC Pin Voltage	$V_{CC}$		2 – 4	– 0.3 to 35	V
FB Pin Voltage	$V_{FB}$		3 – 4	– 0.3 to 10	V
CSS Pin Voltage	$V_{CSS}$		5 – 4	– 0.3 to 12	V
OC Pin Voltage	$V_{OC}$		6 – 4	– 6 to 6	V
RC Pin Voltage	$V_{RC}$		7 – 4	– 6 to 6	V
REG Pin Source Current	$I_{REG}$		8 – 4	– 20.0	mA
RV Pin Current	$I_{RV}$	DC	9 – 4	– 2 to 2	mA
		Pulse 40 ns	9 – 4	– 100 to 100	mA
VGL Pin Voltage	$V_{GL}$		11 – 4	– 0.3 to $V_{REG} + 0.3$	V
Voltage between VB Pin and VS Pin	$V_B - V_S$		14 – 15	– 0.3 to 15.0	V
VS Pin Voltage	$V_S$		15 – 4	– 1 to 600	V
VGH Pin Voltage	$V_{GH}$		16 – 4	$V_S - 0.3$ to $V_B + 0.3$	V
Operating Ambient Temperature	$T_{OP}$		—	– 20 to 85	$^{\circ}\text{C}$
Storage Temperature	$T_{stg}$		—	– 40 to 125	$^{\circ}\text{C}$
Junction Temperature	$T_j$		—	150	$^{\circ}\text{C}$

\*The pin 14, pin 15 and pin 16, are guaranteed 1000 V of ESD withstand voltage (Human body model).  
Other pins are guaranteed 2000V of ESD withstand voltage.

## 2. Electrical Characteristics

Current polarities are defined as follows: current going into the IC (sinking) is positive current (+); and current coming out of the IC (sourcing) is negative current (-).

Unless otherwise specified,  $T_A = 25\text{ }^{\circ}\text{C}$ ,  $V_{CC} = 15\text{ V}$ .

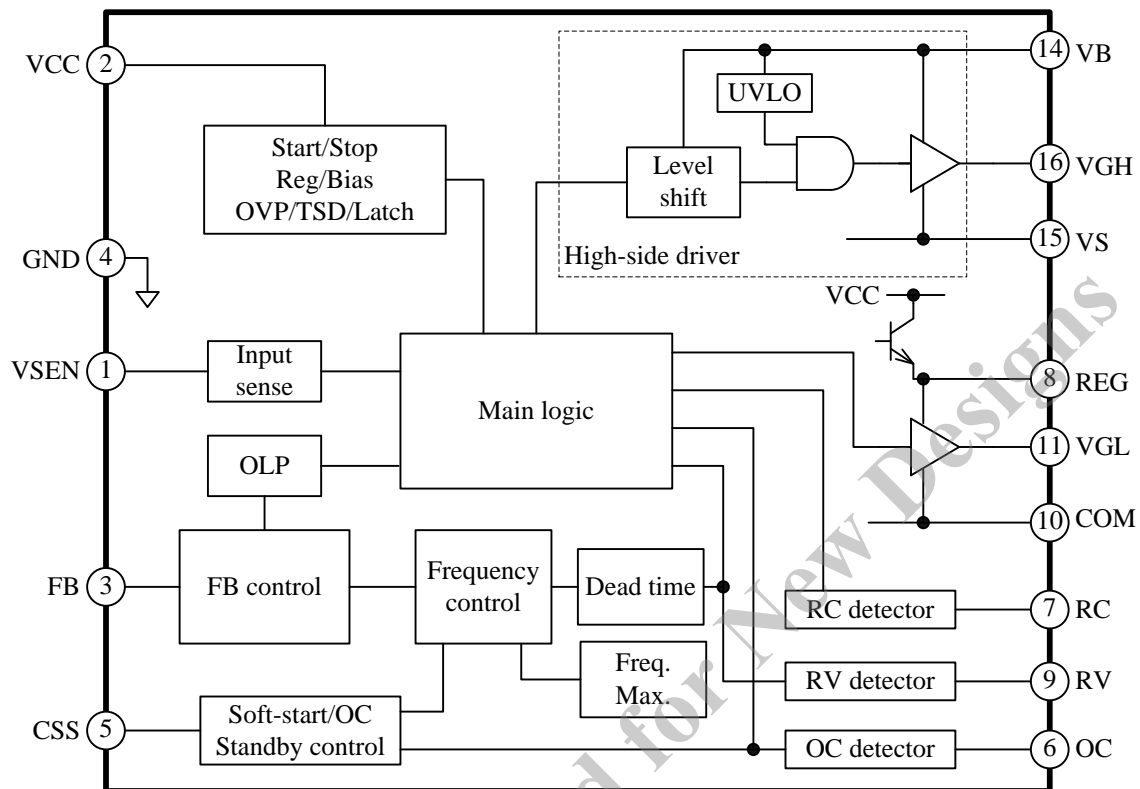
Characteristic	Symbol	Conditions	Pin	Min.	Typ.	Max.	Unit
<b>Startup Circuit and Circuit Current</b>							
Operation Start Voltage	$V_{CC(ON)}$		2 - 4	10.2	11.8	13.0	V
Operation Stop Voltage <sup>(1)</sup>	$V_{CC(OFF)}$		2 - 4	8.8	9.8	10.9	V
Circuit Current in Operation	$I_{CC(ON)}$		2 - 4	—	—	20.0	mA
Circuit Current in Non-operation	$I_{CC(OFF)}$	$V_{CC} = 9\text{ V}$	2 - 4	—	—	1.2	mA
Circuit Current in Latched Shutdown Operation	$I_{CC(L)}$	$V_{CC} = 11\text{ V}$	2 - 4	—	—	1.2	mA
<b>Soft Start</b>							
CSS Pin Charge Current	$I_{CSS(C)}$		5 - 4	-0.21	-0.18	-0.15	mA
CSS Pin Reset Current	$I_{CSS(R)}$	$V_{CC} = 9\text{ V}$	5 - 4	1.0	1.8	2.4	mA
<b>ON / OFF</b>							
CSS Pin Threshold Voltage (2)	$V_{CSS(2)}$	$V_{SEN} = 3\text{ V}$ $V_{OC} = 0\text{ V}$	5 - 4	0.50	0.59	0.68	V
<b>Oscillator</b>							
Minimum Oscillation Frequency	$f_{(MIN)}$	$V_{CC} = 9\text{ V}$	11 - 10 16 - 15	26.2	28.3	31.2	kHz
Maximum Oscillation Frequency	$f_{(MAX)}$	$I_{FB} = -2\text{ mA}$	11 - 10 16 - 15	265	300	335	kHz
Maximum Dead Time	$t_{d(MAX)}$	$V_{SEN} = 3\text{ V}$	11 - 10 16 - 15	1.90	2.45	3.00	$\mu\text{s}$
Minimum Dead Time	$t_{d(MIN)}$	$I_{FB} = -2\text{ mA}$	11 - 10 16 - 15	0.25	0.50	0.75	$\mu\text{s}$
<b>Standby Operation</b>							
Burst Oscillation frequency	$f_{CSS}$	$I_{FB} = -3.5\text{ mA}$	5 - 4	70	105	130	Hz
<b>Feedback control</b>							
FB Pin Source Current at Burst Mode Start	$I_{CONT(1)}$		3 - 4	-2.9	-2.5	-2.1	mA
FB Pin Source Current at Oscillation stop	$I_{CONT(2)}$		3 - 4	-3.7	-3.1	-2.5	mA
<b>Supply of Driver Circuit</b>							
REF Pin Output Voltage	$V_{REG}$	$I_{FB} = -2\text{ mA}$	8 - 4	9.9	10.5	11.1	V
<b>High-side Drive Circuit</b>							
High-side Driver Operation Start Voltage	$V_{BUV(ON)}$		14 - 15	6.3	7.3	8.3	V
High-side Driver Operation Stop Voltage	$V_{BUV(OFF)}$		14 - 15	5.5	6.4	7.2	V
<b>Drive Circuit</b>							
Source Current 1 of VGL Pin and VGH Pin	$I_{GL\_SOURCE1}$ $I_{GH\_SOURCE1}$	$V_{REG} = 10.5\text{ V}$ $V_B = 10.5\text{ V}$ $V_{GL} = 0\text{ V}$ $V_{GH} = 0\text{ V}$	11 - 10 16 - 15	—	-515	—	mA

<sup>(1)</sup>  $V_{CC(OFF)} < V_{CC(ON)}$

Characteristic	Symbol	Conditions	Pin	Min.	Typ.	Max.	Unit
Sink Current 1 of VGL Pin and VGH Pin	$I_{GL\_SINK1}$ $I_{GH\_SINK1}$	$V_{REG} = 10.5V$ $V_B = 10.5V$ $V_{GL} = 10.5V$ $V_{GH} = 10.5V$	11 – 10 16 – 15	—	685	—	mA
Source Current 2 of VGL Pin and VGH Pin	$I_{GL\_SOURCE2}$ $I_{GH\_SOURCE2}$	$V_{REG} = 12V$ $V_B = 12V$ $V_{GL} = 10.5V$ $V_{GH} = 10.5V$	11 – 10 16 – 15	–120	–85	–50	mA
Sink Current 2 of VGL Pin and VGH Pin	$I_{GL\_SINK2}$ $I_{GH\_SINK2}$	$V_{REG} = 12V$ $V_B = 12V$ $V_{GL} = 1.5V$ $V_{GH} = 1.5V$	11 – 10 16 – 15	70	113	160	mA
<b>Brown-in / Brown-out Function</b>							
VSEN Pin Threshold Voltage (ON)	$V_{SEN(ON)}$		1 – 4	1.32	1.42	1.52	V
VSEN Pin Threshold Voltage (OFF)	$V_{SEN(OFF)}$		1 – 4	1.08	1.16	1.24	V
<b>Detection of Voltage Resonant</b>							
Voltage Resonant Detection Voltage (1)	$V_{RV(1)}$		9 – 4	3.8	4.9	5.4	V
Voltage Resonant Detection Voltage (2)	$V_{RV(2)}$		9 – 4	1.20	1.77	2.30	V
<b>Detection of Current Resonant and OCP</b>							
Capacitive Mode Operation Detection Voltage	$V_{RC}$		7 – 4	0.055	0.155	0.255	V
				–0.255	–0.155	–0.055	V
RC Pin Threshold Voltage (High Speed)	$V_{RC(S)}$		7 – 4	2.15	2.35	2.55	V
				–2.55	–2.35	–2.15	V
OC Pin Threshold Voltage (Low)	$V_{OC(L)}$	$V_{CSS} = 3V$	6 – 4	1.42	1.52	1.62	V
OC Pin Threshold Voltage (High)	$V_{OC(H)}$	$V_{CSS} = 3V$	6 – 4	1.69	1.83	1.97	V
OC Pin Threshold Voltage (High Speed)	$V_{OC(S)}$	$V_{CSS} = 5V$	6 – 4	2.15	2.35	2.55	V
$C_{SS}$ Pin Sink Current (Low)	$I_{CSS(L)}$	$V_{CSS} = 3V$ $V_{OC} = 1.65V$	5 – 4	1.0	1.8	2.4	mA
$C_{SS}$ Pin Sink Current (High)	$I_{CSS(H)}$	$V_{CSS} = 3V$ $V_{OC} = 2V$	5 – 4	12.0	20.0	28.0	mA
$C_{SS}$ Pin Sink Current (High Speed)	$I_{CSS(S)}$	$V_{RC} = 2.8V$	5 – 4	11.0	18.3	25.0	mA
<b>OLP Latch and External Latch</b>							
FB Pin Source Current	$I_{FB}$	$V_{FB} = 5V$	3 – 4	–30.5	–25.5	–20.5	μA
FB Pin Threshold Voltage	$V_{FB}$		3 – 4	6.55	7.05	7.55	V
CSS Pin Threshold Voltage (1)	$V_{CSS(1)}$		5 – 4	7.0	7.8	8.6	V
Latched Circuit Release VCC Voltage <sup>(2)</sup>	$V_{CC(LA\_OFF)}$		2 – 4	6.7	8.2	9.5	V
<b>OVP and TSD</b>							
VCC Pin OVP Threshold Voltage	$V_{CC(OVP)}$	$V_{SEN} = 3V$	2 – 4	28.0	31.0	34.0	V
Thermal Shutdown Temperature	$T_j(TSD)$		—	150	—	—	°C
<b>Thermal Resistance</b>							
Thermal Resistance Junction to Ambient	$\theta_{j-A}$		—	—	—	95	°C/W

<sup>(2)</sup>  $V_{CC(LA\_OFF)} < V_{CC(OFF)}$

3. Block Diagram

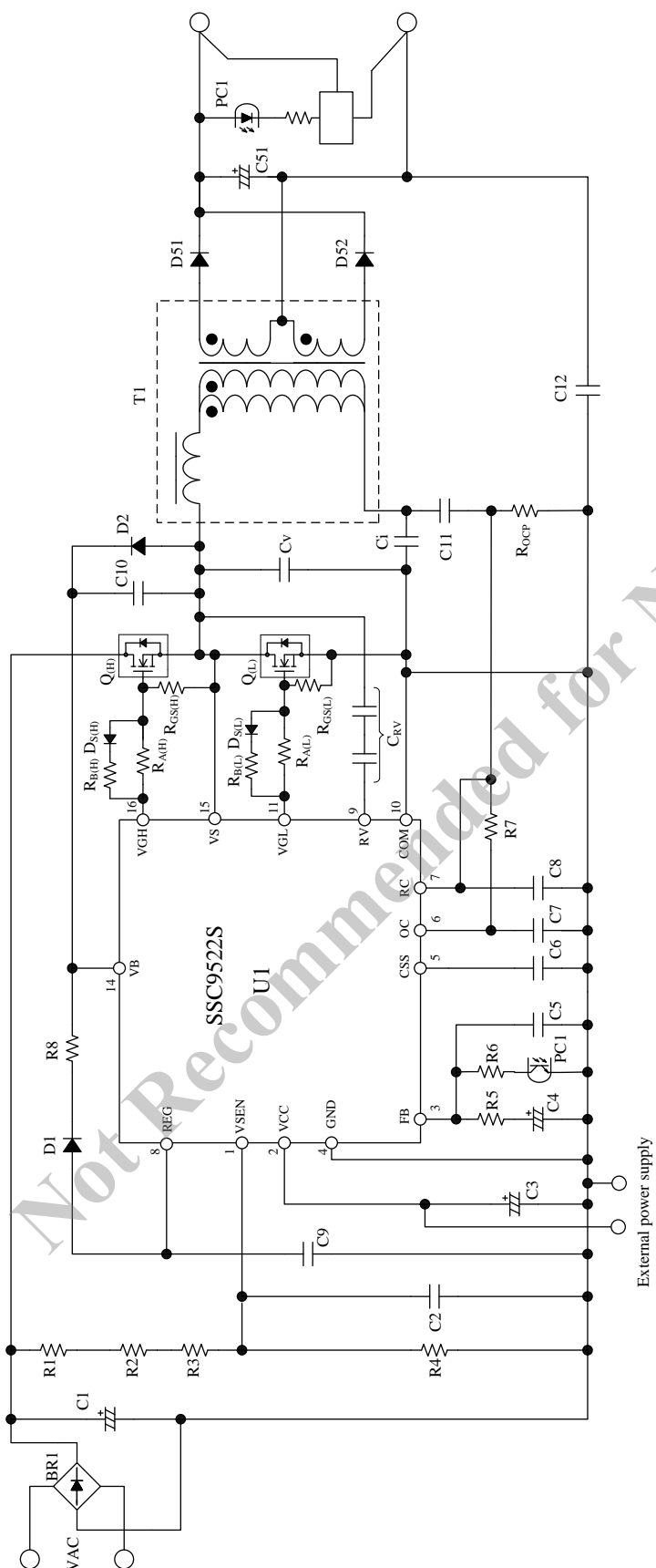


4. Pin Configuration Definitions

Number	Name	Function
1	VSEN	AC input voltage detection signal input
2	VCC	Power supply voltage input for the IC, and Overvoltage Protection (OVP) signal input
3	FB	Feedback signal input for constant voltage control signal, and Overload Protection (OLP) signal input
4	GND	Ground for control part
5	CSS	Soft start capacitor connection
6	OC	Overcurrent Protection (OCP) signal input
7	RC	Resonant current detection signal input
8	REG	Power supply output for high-side gate drive
9	RV	Resonant voltage detection signal input
10	COM	Ground for power part
11	VGL	Low-side gate drive output
12, 13	(NC)	—
14	VB	Power supply input for high-side gate drive
15	VS	Floating ground for high-side driver
16	VGH	High-side gate drive output
17, 18	(NC)	—

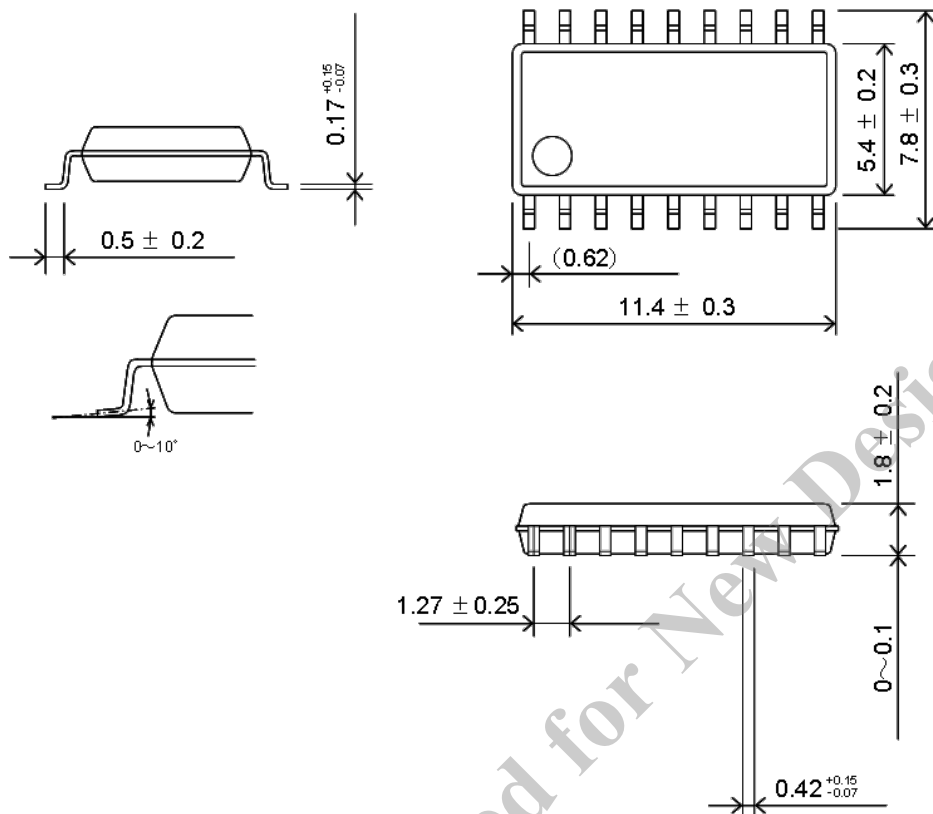
Number	Name	Function
1	VSEN	AC input voltage detection signal input
2	VCC	Power supply voltage input for the IC, and Overvoltage Protection (OVP) signal input
3	FB	Feedback signal input for constant voltage control signal, and Overload Protection (OLP) signal input
4	GND	Ground for control part
5	CSS	Soft start capacitor connection
6	OC	Overcurrent Protection (OCP) signal input
7	RC	Resonant current detection signal input
8	REG	Power supply output for high-side gate drive
9	RV	Resonant voltage detection signal input
10	COM	Ground for power part
11	VGL	Low-side gate drive output
12, 13	(NC)	—
14	VB	Power supply input for high-side gate drive
15	VS	Floating ground for high-side driver
16	VGH	High-side gate drive output
17, 18	(NC)	—

## 5. Typical Application



## 6. Physical Dimensions

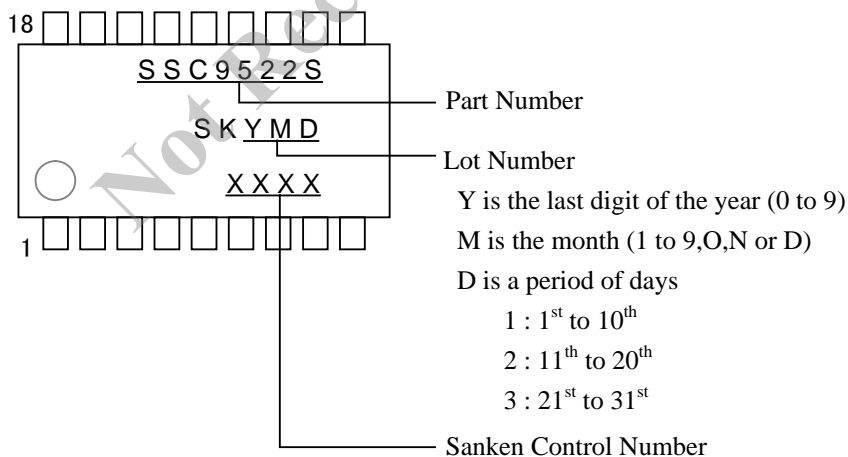
- SOP18



### NOTES:

- Dimension is in millimeters
- Pb-free (RoHS compliant)

## 7. Marking Diagram



## 8. Operational Description

All of the parameter values used in these descriptions are typical values, unless they are specified as minimum or maximum. Current polarities are defined as follows: current going into the IC (sinking) is positive current (+); and current coming out of the IC (sourcing) is negative current (-).  $Q_{(H)}$  and  $Q_{(L)}$  indicate a high-side power MOSFET and a low-side power MOSFET respectively.  $C_i$  and  $C_v$  indicate a current resonant capacitor and a voltage resonant capacitor respectively.

### 8.1 Resonant Circuit Operation

Figure 8-1 shows a basic RLC series resonant circuit.

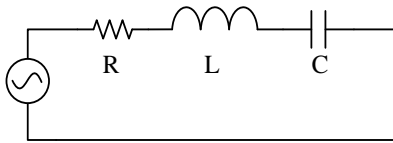


Figure 8-1. RLC Series Resonant Circuit

The impedance of the circuit,  $\hat{Z}$ , is as the following Equation.

$$\hat{Z} = R + j\left(\omega L - \frac{1}{\omega C}\right) \quad (1)$$

where,  $\omega$  is angular frequency and  $\omega = 2\pi f$ .

$$\hat{Z} = R + j\left(2\pi f L - \frac{1}{2\pi f C}\right) \quad (2)$$

When the frequency,  $f$ , changes, the impedance of resonant circuit will change as shown in Figure 8-2

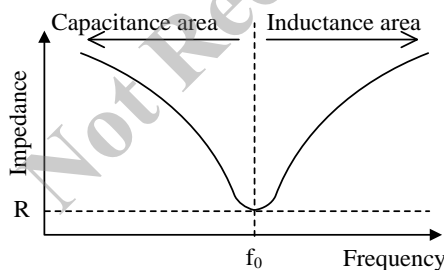


Figure 8-2. Impedance of Resonant Circuit

In Equation (2),  $\hat{Z}$  becomes minimum value (= R) at  $2\pi f L = 1/2\pi f C$ , and then  $\omega$  is calculated by Equation (3).

$$\omega = 2\pi f = \frac{1}{\sqrt{LC}} \quad (3)$$

The frequency in which  $\hat{Z}$  becomes minimum value is the resonant frequency,  $f_0$ . The higher frequency area than  $f_0$  is the inductance area, and the lower frequency area than  $f_0$  is the capacitance area.

From Equation (3),  $f_0$  is as follows;

$$f_0 = \frac{1}{2\pi\sqrt{LC}} \quad (4)$$

Figure 8-3 shows the circuit of a current resonant power supply. The basic configuration of the current resonant power supply is a half-bridge converter. The switching device  $Q_{(H)}$  and  $Q_{(L)}$  are connected in series with  $V_{IN}$ . The series resonant circuit and the voltage resonant capacitor  $C_v$  are connected in parallel with  $Q_{(L)}$ . The series resonant circuit is comprised of a resonant inductor  $L_R$ , a primary winding P of a transformer T1 and a current resonant capacitor  $C_i$ .

In the resonant transformer T1, the coupling between primary winding and secondary winding is designed to be poor so that the leakage inductance increases. By using it as  $L_R$ , the series resonant circuit can be down sized. The dotted mark in T1 shows the winding polarity, the secondary windings S1 and S2 are connected so that the polarities are set to the same position shown in Figure 8-3, and the winding numbers of each other are equal.

From Equation (1), the impedance of current resonant power supply is calculated by Equation (5). From Equation (4), the resonant frequency,  $f_0$ , is calculated by Equation (6).

$$\hat{Z} = R + j\left\{\omega(L_R + L_P) - \frac{1}{\omega C_i}\right\} \quad (5)$$

$$f_0 = \frac{1}{2\pi\sqrt{(L_R + L_P) \times C_i}} \quad (6)$$

where,

R: the equivalent resistance of load

$L_R$ : the inductance of the resonant inductor

$L_P$ : the inductance of the primary winding P

$C_i$ : the capacitance of current resonant capacitor

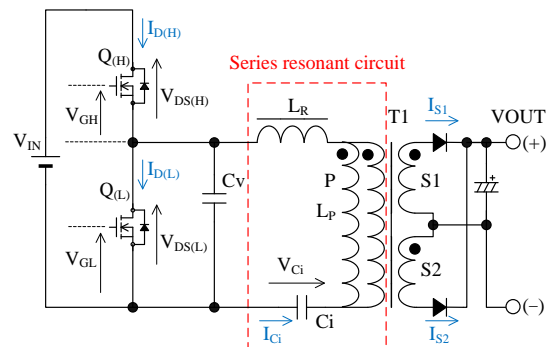


Figure 8-3. Current Resonant Power Supply Circuit



In the current resonant power supply,  $Q_{(H)}$  and  $Q_{(L)}$  are alternatively turned on and off. The on time and off time of them are equal. There is a dead time between  $Q_{(H)}$  on period and  $Q_{(L)}$  on period. During the dead time, both  $Q_{(H)}$  and  $Q_{(L)}$  are in off status.

The current resonant power supply is controlled by the frequency control. When the output voltage decreases, the IC makes the switching frequency low so that the output power is increased and the output voltage is kept constant. This control must operate in the inductance area ( $f_{sw} > f_0$ ). Since the winding current is delayed from the winding voltage in the inductance area, the turn-on operation is ZCS (Zero Current Switching) and the turn-off operation is ZVS (Zero Voltage Switching). Thus, the switching loss of  $Q_{(H)}$  and  $Q_{(L)}$  is nearly zero,

In the capacitance area ( $f_{sw} < f_0$ ), the current resonant power supply operates as follows. When the output voltage decreases, the switching frequency is decreased, and then the output power is more decreased. Thus, the output voltage cannot be kept constant. Since the winding current goes ahead of the winding voltage in the capacitance area, the operation with hard switching occurs in  $Q_{(H)}$  and  $Q_{(L)}$ . Thus, the power loss increases.

This operation in the capacitance area is called the capacitive mode operation. The current resonant power supply must be operated without the capacitive mode operation (refer to Section 8.7 about details of it).

Figure 8-4 shows the basic operation waveform of current resonant power supply (see Figure 8-3 about the symbol in Figure 8-4). The current resonant waveforms in normal operation are divided a period A to a period F. The current resonant power supply operates in the each period as follows.

In following description,

$I_{D(H)}$  is the current of  $Q_{(H)}$ ,

$I_{D(L)}$  is the current of  $Q_{(L)}$ ,

$V_{F(H)}$  is the forward voltage of  $Q_{(H)}$ ,

$V_{F(L)}$  is the forward voltage of  $Q_{(L)}$ ,

$I_L$  is the current of  $L_R$ ,

$V_{IN}$  is an input voltage,

$V_{Ci}$  is  $C_i$  voltage, and

$V_{Cv}$  is  $C_v$  voltage.

#### 1) Period A

When  $Q_{(H)}$  is ON, energy is stored into the series resonant circuit by  $I_{D(H)}$  flowing through the resonant circuit and the transformer as shown in Figure 8-5. At the same time, the energy is transferred to the secondary circuit. When the primary winding voltage can not keep the secondary rectifier ON, the energy to the secondary circuit is stopped.

#### 2) Period B

After the secondary side current becomes zero, the resonant current flows to the primary side only as shown in Figure 8-6 and  $C_i$  is charged by it.

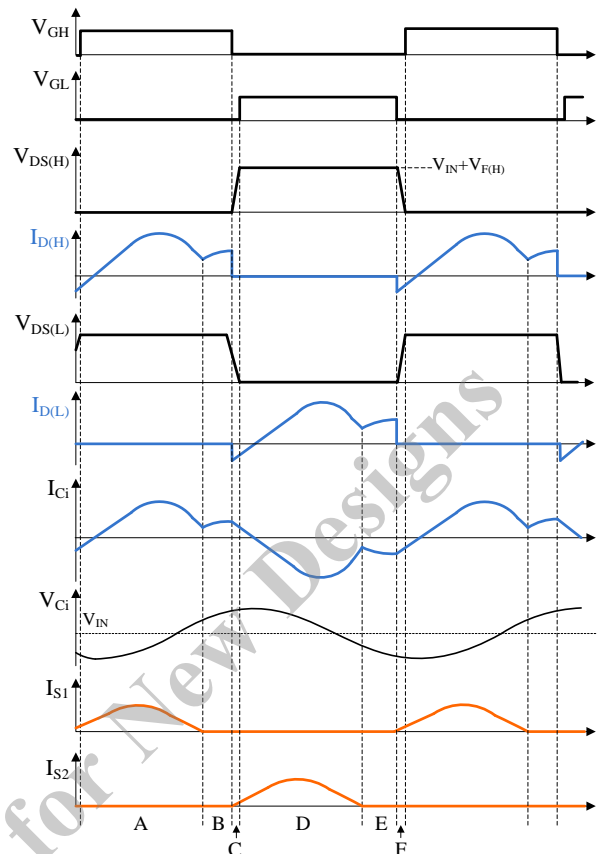


Figure 8-4. The Basic Operation Waveforms of Current Resonant Power Supply

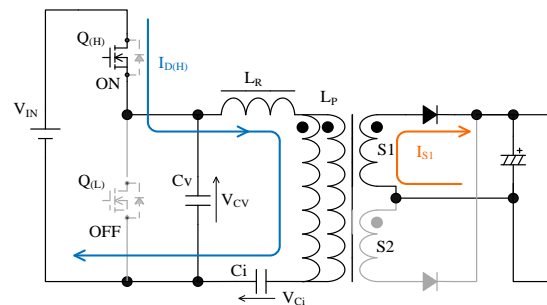


Figure 8-5. Operation in Period A

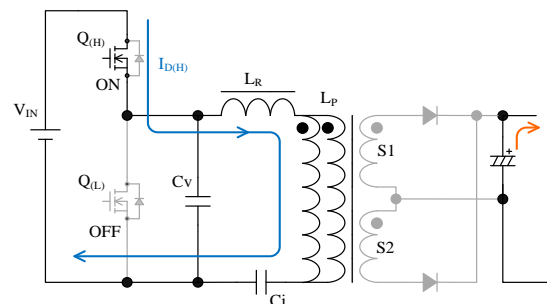


Figure 8-6. Operation in Period B

## 3) Period C

Period C is the dead-time. Both  $Q_{(H)}$  and  $Q_{(L)}$  are in off-state.

When  $Q_{(H)}$  turns off,  $I_L$  is flowed by the energy stored in the series resonant circuit as shown in Figure 8-7, and  $C_V$  is discharged. When  $V_{CV}$  decreases to  $V_{F(L)}$ ,  $-I_{D(L)}$  flows through the body diode of  $Q_{(L)}$  and  $V_{CV}$  is clamped to  $V_{F(L)}$ .

After that,  $Q_{(L)}$  turns on. Since  $V_{DS(L)}$  is nearly zero at the point,  $Q_{(L)}$  operates in ZVS and ZCS. Thus, switching loss is nearly zero.

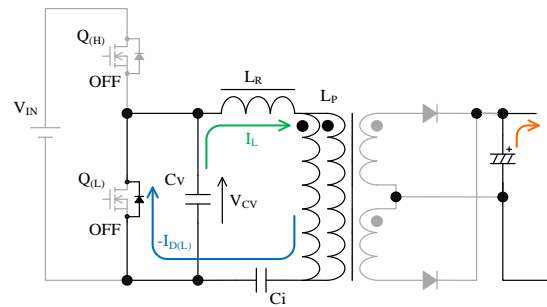


Figure 8-7. Operation in Period C

## 4) Period D

When  $Q_{(L)}$  turns on,  $I_{D(L)}$  flows as shown in Figure 8-8 and the primary winding voltage of the transformer adds  $V_{Ci}$ . At the same time, energy is transferred to the secondary circuit. When the primary winding voltage can not keep the secondary rectifier ON, the energy to the secondary circuit is stopped.

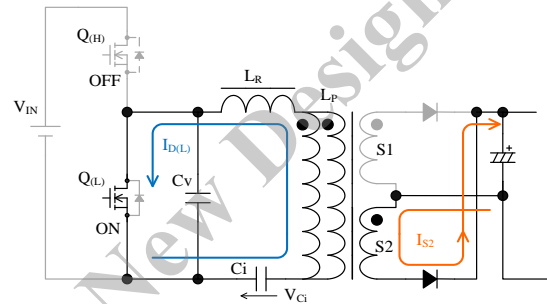


Figure 8-8. Operation in Period D

## 5) Period E

After the secondary side current becomes zero, the resonant current flows to the primary side only as shown in Figure 8-9 and  $C_i$  is charged by it.

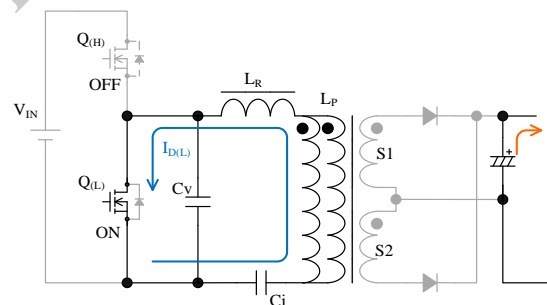


Figure 8-9. Operation in Period E

## 6) Period F

This period is the dead-time. Both  $Q_{(H)}$  and  $Q_{(L)}$  are in off-state.

When  $Q_{(L)}$  turns off,  $-I_L$  is flowed by the energy stored in the series resonant circuit as shown in Figure 8-10.  $C_V$  is discharged. When  $V_{CV}$  decreases to  $V_{IN} + V_{F(H)}$ ,  $-I_{D(H)}$  flows through body diode of  $Q_{(H)}$  and  $V_{CV}$  is clamped to  $V_{IN} + V_{F(H)}$ .

After that,  $Q_{(H)}$  turns on. Since  $V_{DS(H)}$  is nearly zero at the point,  $Q_{(H)}$  operates in ZVS and ZCS. Thus, the switching loss is nearly zero.

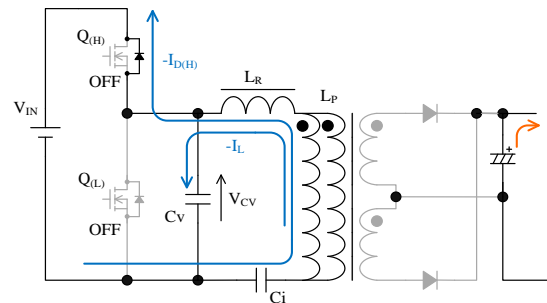


Figure 8-10. Operation in Period F

## 7) After the Period F

Then,  $I_{D(H)}$  flows and the operation returns to the period A.

The above operation is repeated, the energy is transferred to the secondary side from the resonant circuit.

## 8.2 Startup Operation

Figure 8-11 shows the VCC pin peripheral circuit with Brown-in and Brown-out Function, Figure 8-12 shows the VCC pin peripheral circuit without Brown-in and Brown-out Function (see Section 8.8 about Brown-in and Brown-out Function).

The VCC pin is a power supply input pin for a control circuit and is supplied from an external power supply. In Figure 8-13, when the VCC pin increases to the Operation Start Voltage,  $V_{CC(ON)} = 11.8$  V, the control circuit starts operation. When the VCC pin decreases to the Operation Stop Voltage,  $V_{CC(OFF)} = 9.8$  V, the control circuit is stopped by Undervoltage Lockout (UVLO) circuit, and returns to the state before startup.

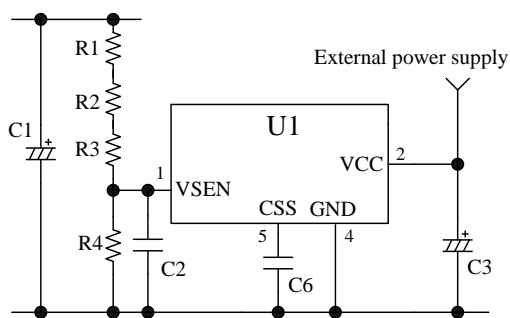


Figure 8-11. VCC Pin Peripheral Circuit with Brown-in and Brown-out Function

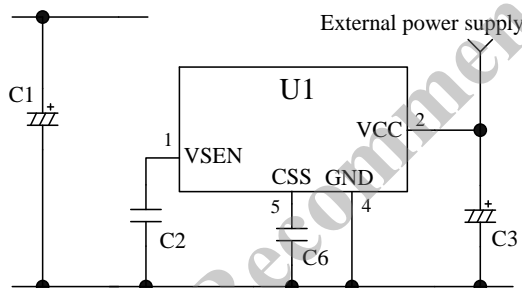


Figure 8-12. VCC Pin Peripheral Circuit without Brown-in and Brown-out Function

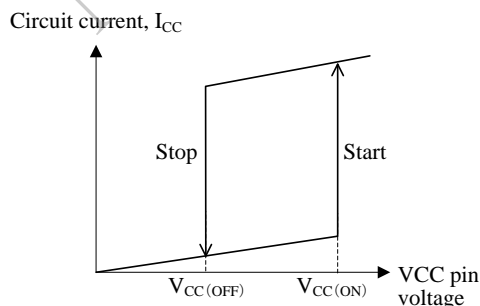


Figure 8-13. Relationship between VCC Pin Voltage and  $I_{CC}$

In startup operation, the IC starts a switching operation when the IC satisfies all conditions below as shown in Figure 8-14.

VCC pin voltage  $\geq V_{CC(ON)} = 11.8$  V

VSEN pin voltage  $\geq V_{SEN(ON)} = 1.42$  V

CSS pin voltage  $\geq V_{CSS(2)} = 0.59$  V

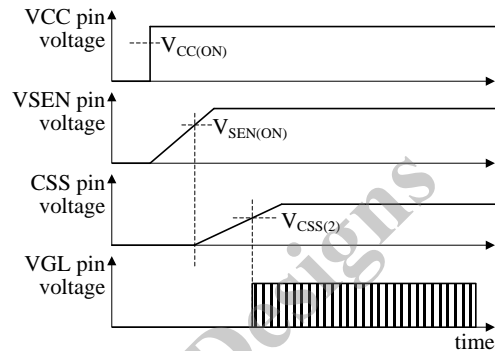


Figure 8-14. Startup Waveforms

When the IC is supplied by the external power supply,  $t_{ST}$  is calculated by Equation (7).

$t_{ST}$  is the total startup time until the IC starts a switching operation after VCC pin voltage reaches  $V_{CC(ON)}$ .

- With Brown-in and Brown-out Function

$$t_{ST} = t_{ST1} = \frac{C6 \times V_{CSS(2)}}{|I_{CSS(C)}|} \quad (7)$$

where,  $V_{CSS(2)}$  is 0.59 V and  $I_{CSS(C)}$  is -0.18 mA. If C6 is 1  $\mu$ F,  $t_{ST}$  becomes about 3.3 ms.

- Without Brown-in and Brown-out Function

In this case,  $t_{ST}$  is a value of adding  $t_{ST1}$  calculated by Equation (7) to  $t_{ST2}$  calculated by Equation (8). The period that until the VSEN pin voltage reaches to  $V_{SEN(ON)} = 1.42$  V after the VCC pin voltage reaches  $V_{CC(ON)}$  is defined as  $t_{ST2}$ .

$$t_{ST2} = C2 \times 380k \quad (8)$$

If C6 is 1  $\mu$ F and C2 is 0.01  $\mu$ F,  $t_{ST1}$  becomes 3.3ms and  $t_{ST2}$  becomes about 3.8 ms.

Thus,  $t_{ST}$  is  $t_{ST1} + t_{ST2} = 7.1$  ms.



## 8.6 Automatic Dead Time Adjustment Function

As shown in Figure 8-18, if the dead time is shorter than the voltage resonant period, the power MOSFET is turned on and off during the voltage resonant operation. In this case, the power MOSFET turned on and off in hard switching operation, and the switching loss increases. The Automatic Dead Time Adjustment Function is the function that the ZVS (Zero Voltage Switching) operation of  $Q_{(H)}$  and  $Q_{(L)}$  is controlled automatically by the voltage resonant period detection of IC. The voltage resonant period is varied by the power supply specifications (input voltage and output power, etc.). However, the power supply with this function is unnecessary to adjust the dead time for each power supply specification.

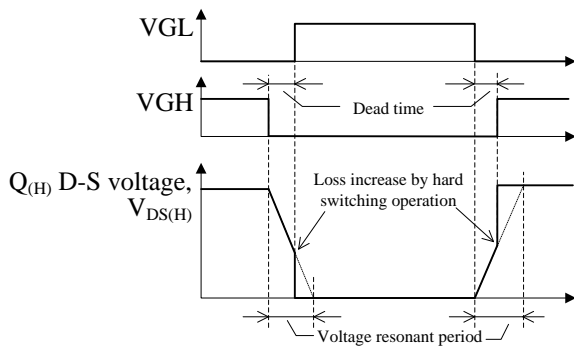


Figure 8-18. ZVS Failure Operation Waveform

Figure 8-19 shows the RV pin peripheral circuit and the internal dead time detection circuit. The external components for this function is only high-voltage ceramic capacitor,  $C_{RV}$ , connected between the VS pin and the RV pin. The value of  $C_{RV}$  is about 5 pF.

The RV pin voltage is the divided voltage by resistors between the internal reference voltage, Reg, and the GND pin. When the drain to source voltage of  $Q_{(L)}$ ,  $V_{DS(L)}$ , increases, the differential current,  $\Delta i$ , flows through  $C_{RV}$  (refer to Figure 8-20). The  $dv/dt$  when  $V_{DS(L)}$  increases is detected by  $\Delta i$  input to the RV pin. Since SW1 and SW2 turn on necessary period, the IC circuit current reduction and the differential circuit response improvement are achieved.

$\Delta i$  is calculated by Equation (9). The  $C_{RV}$  should be adjusted in all condition including transient state so that  $\Delta i$  satisfies Equation (10).

If  $\Delta i$  is large, the capacitance of  $C_{RV}$  is adjusted small. When  $dt$  is under 40 ns,  $\Delta i$  is  $\pm 100$  mA.

$$\Delta i = C_{RV} \times \left( \frac{dv}{dt} \right) \quad (9)$$

$$|\Delta i| \leq \frac{100 \text{ (mA)} \times 40 \text{ (ns)}}{dt} \quad (10)$$

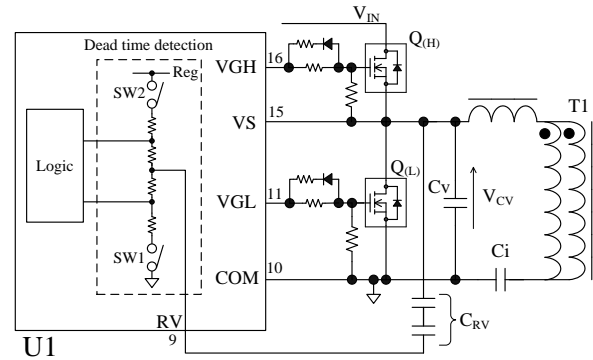


Figure 8-19. RV Pin Peripheral Circuit and Dead Time Detection Circuit

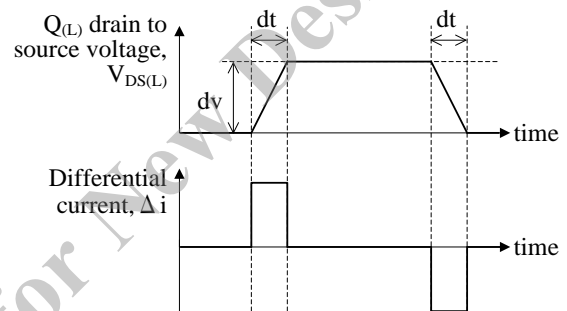


Figure 8-20. Differential Current Waveforms

Figure 8-21 shows the operating waveform of the Automatic Dead Time Adjustment Function. When  $Q_{(L)}$  and  $Q_{(H)}$  turn off, this function operates as follows:

### • $Q_{(L)}$ Turns Off

After  $Q_{(L)}$  turns off, SW2 is turned on while SW1 is kept on state. The resonant current flows through  $C_V$ ,  $C_i$  and  $T1$  (refer to Figure 8-19) and the  $C_V$  voltage,  $V_{CV}$ , increases from 0 V. When  $V_{CV}$  becomes Equation (11), the resonant current flows through the body diode of  $Q_{(H)}$  and  $V_{CV}$  is clamped  $V_{IN} + V_{F(H)}$ . The period that until  $V_{CV}$  is clamped after  $V_{CV}$  starts to increase is defined as the voltage resonant period.

$$V_{CV} \geq V_{IN} + V_{F(H)} \quad (11)$$

Where,  $V_{IN}$  is input voltage and  $V_{F(H)}$  is the forward voltage of the body diode of  $Q_{(H)}$

In this time, the differential current,  $\Delta i$ , flows through  $C_{RV}$ . The RV pin voltage increases from the voltage divided by internal resistors and becomes internal clamped voltage. When the voltage resonant period finishes and flowing  $\Delta i$  finishes, the RV pin voltage starts to decrease. When the RV pin voltage becomes the Voltage Resonant Detection Voltage (1),  $V_{RV(1)} = 4.9$  V,  $Q_{(H)}$  is turned on and SW1 is turned off.



The period that until SW1 is turned off after SW2 is turned on is defined as the automatically adjusted dead time.

#### • $Q_{(H)}$ Turns Off

After  $Q_{(H)}$  turns off, SW1 is turned on while SW2 is kept on state. The resonant current flows through  $C_V$ ,  $C_i$  and  $T_1$  (refer to Figure 8-19) and the  $C_V$  voltage,  $V_{CV}$ , decrease from the input voltage,  $V_{IN}$ .

When  $V_{CV}$  becomes Equation (12), the resonant current flows through the body diode of  $Q_{(L)}$  and  $V_{CV}$  is clamped  $-V_{F(L)}$ . The period that until  $V_{CV}$  is clamped after  $V_{CV}$  starts to decrease is defined as the voltage resonant period.

$$V_{CV} \leq -V_{F(L)} \quad (12)$$

Where,  $V_{F(L)}$  is the forward voltage of the body diode of  $Q_{(L)}$ .

In this time, the differential current,  $\Delta i$ , flows through  $C_{RV}$ . The RV pin voltage decreases from the voltage divided by internal resistors and becomes about the ground voltage. When the voltage resonant period finishes and flowing  $\Delta i$  finishes, the RV pin voltage starts to increase. When the RV pin voltage becomes the Voltage Resonant Detection Voltage (2),  $V_{RV(2)} = 1.77 \text{ V}$ ,  $Q_{(L)}$  is turned on and SW2 is turned off. The period until SW2 is turned off after SW1 is turned on is defined as the automatically adjusted dead time.

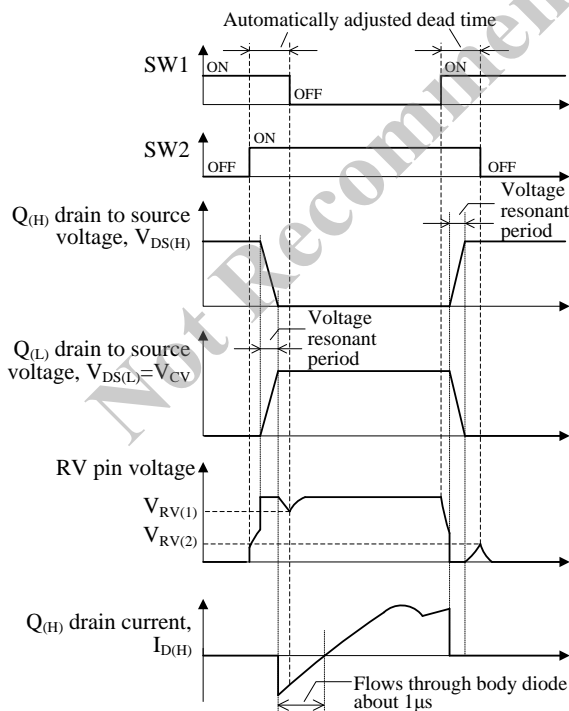


Figure 8-21. Automatic Dead Time Adjustment Function Operating Waveforms

When the RV pin is inputted the signal of  $V_{RV(1)}$  and  $V_{RV(2)}$ , the IC is controlled ZVS (Zero Voltage Switching) always by the Automatic Dead Time Adjustment Function.

In minimum output power at maximum input voltage and maximum output power at minimum input voltage, the ZCS (Zero Current Switching) operation of IC (the drain current flows through the body diode is about  $1 \mu\text{s}$  as shown in Figure 8-21), should be checked based on actual operation in the application.

## 8.7 Capacitive Mode Operation Detection Function

The resonant power supply is operated in the inductance area shown in Figure 8-22. In the capacitance area, the power supply becomes the capacitive mode operation (refer to Section 8.1). In order to prevent the operation, the minimum oscillation frequency is needed to be set higher than  $f_0$  on each power supply specification.

However, the IC has the capacitive mode operation Detection Function kept the frequency higher than  $f_0$ . Thus, the minimum oscillation frequency setting is unnecessary and the power supply design is easier. In addition, the ability of transformer is improved because the operating frequency can operate close to the resonant frequency,  $f_0$ .

The RC pin detects the resonant current, and the capacitive mode operation is prevented. The Capacitive Mode Operation Detection Function operations as follows:

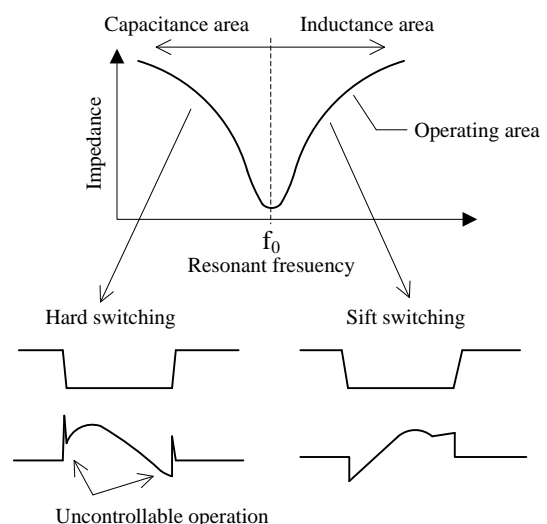


Figure 8-22. Operating Area of Resonant Power Supply

### • Period in which the $Q_{(H)}$ is ON

Figure 8-23 shows the RC pin waveform in the inductance area, and Figure 8-24 shows the RC pin waveform in the capacitance area.

In the inductance area, the RC pin voltage doesn't cross  $V_{RC} = +0.155$  V in the downward direction during the on period of  $Q_{(H)}$  as shown in Figure 8-23.

On the contrary, in the capacitance area, the RC pin voltage crosses  $V_{RC} = +0.155$  V in the downward direction. At this point, the capacitive mode operation is detected. Thus,  $Q_{(H)}$  is turned off, and  $Q_{(L)}$  is turned on, as shown in Figure 8-24.

### • Period in which the $Q_{(L)}$ is On

Contrary to the above of  $Q_{(H)}$ , in the capacitance area, the RC pin voltage crosses  $V_{RC} = -0.155$  V in the upward direction during the on period of  $Q_{(L)}$ . At this point, the capacitive mode operation is detected. Thus,  $Q_{(L)}$  is turned off and  $Q_{(H)}$  is turned on.

As above, since the capacitive mode operation is detected by pulse-by-pulse and the operating frequency is synchronized with the frequency of the capacitive mode operation, and the capacitive mode operation is prevented.

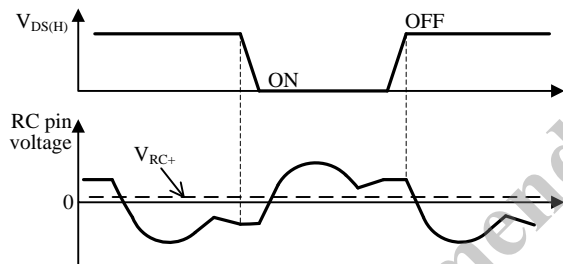


Figure 8-23. RC Pin Voltage in Inductance Area

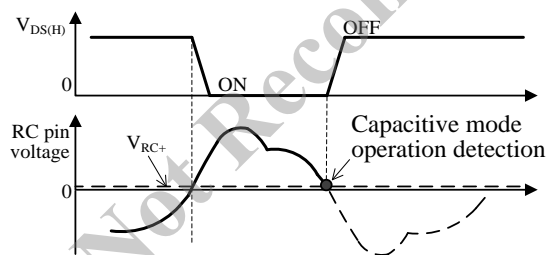


Figure 8-24. RC Pin Voltage in Capacitance Area

In order to quicken detection speed of the capacitive mode operation, the RC pin is connected before the filter circuit of the OC pin as shown in Figure 8-25. C8 is for preventing malfunction caused by noise. The value of C8 is about 100 pF.

The value of  $R_{OCP}$  and C11 should be adjusted so that the RC pin voltage reaches to  $V_{RC} = \pm 0.155$  V in the condition that the IC operation becomes the capacitive mode operation easily (startup operation, input voltage

off, output short and dynamically output power changing). In addition, the RC pin voltage should be within the absolute maximum voltage  $\pm 6$  V.

Since  $R_{OCP}$  and C11 are used by Overcurrent Protection (OCP), these values should take account of OCP. If the RC pin voltage becomes more than the RC pin threshold voltage (High speed),  $V_{RC(S)} = 2.35$  V, or less than  $V_{RC(S)} = -2.35$  V, OCP becomes active (refer to Section 8.9).

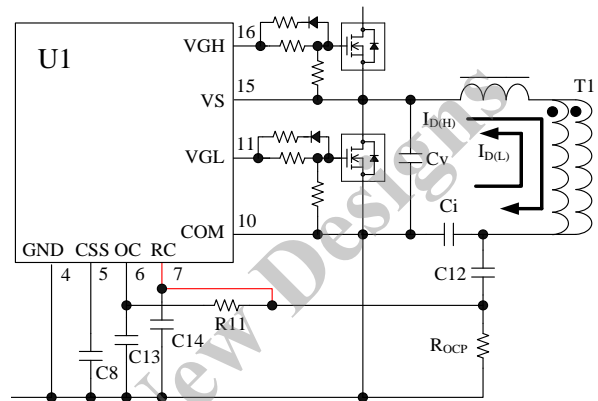


Figure 8-25. RC pin peripheral circuit

## 8.8 Brown-in and Brown-out Function

When the input voltage decreases, the switching operation of the IC is stopped by Brown-in and Brown-out Function. This function prevents excessive input current and overheats.

The detection voltage of Brown-in and Brown-out Function is set by R1 to R4 shown in Figure 8-26. When the VCC pin voltage is higher than  $V_{CC(ON)}$ , this function operates depending on the VSEN pin voltage as follows:

- When the VSEN pin voltage is more than  $V_{SEN(ON)} = 1.42$  V, the IC starts.
- When the VSEN pin voltage is less than  $V_{SEN(OFF)} = 1.16$  V, the IC stops switching operation.

Given, the DC input voltage when the IC starts as  $V_{IN(ON)}$ , the DC input voltage when the switching operation of the IC stops as  $V_{IN(OFF)}$ .  $V_{IN(ON)}$  is calculated by Equation (13).  $V_{IN(OFF)}$  is calculated by Equation (14). Thus, the relationship between  $V_{IN(ON)}$  and  $V_{IN(OFF)}$  is Equation (15).

$$V_{IN(ON)} \doteq V_{SEN(ON)} \times \frac{(R1 + R2 + R3 + R4)}{R4} \quad (13)$$

$$V_{IN(OFF)} \doteq V_{SEN(OFF)} \times \frac{(R1 + R2 + R3 + R4)}{R4} \quad (14)$$

$$V_{IN(OFF)} \doteq \frac{V_{SEN(OFF)}}{V_{SEN(ON)}} \times V_{IN(ON)} \quad (15)$$

The detection resistance is calculated from Equation (13) as follows:

$$R1 + R2 + R3 \doteq \frac{V_{IN(ON)} - V_{SEN(ON)}}{V_{SEN(ON)}} \times R4 \quad (16)$$

Because R1, R2, and R3 are applied high DC voltage and are high resistance, the following should be considered:

- Select a resistor designed against electromigration according to the requirement of the application, or
- Use a combination of resistors in series for that to reduce each applied voltage

C2 shown in Figure 8-26 is for reducing ripple voltage of detection voltage and making delay time. The value of C2 is about 0.1  $\mu$ F.

The value of R1 to R4 and C2 should be selected based on actual operation in the application.

When the Brown-in and Brown-out Function does not be used, the detection resistance (R1, R2, R3, and R4) is removed. C2 is for preventing malfunction caused by noise. The value of C2 is about 0.01  $\mu$ F.

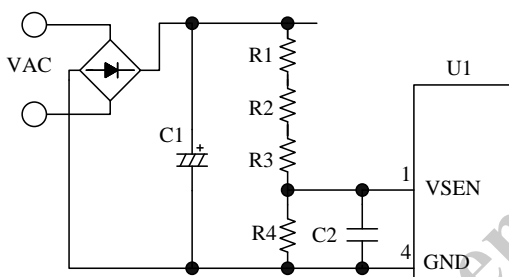


Figure 8-26. VSEN Pin Peripheral Circuit

## 8.9 External Latched Shutdown Function

Figure 8-27 shows the CSS pin peripheral circuit example. When the voltage is inputted to the CSS pin from an external power supply, External Latched Shutdown Function is activated, the IC stops switching operation in the latch mode. When the VCC pin voltage is decreased to  $V_{CC(LA\_OFF)} = 8.2$  V or less, the latch mode is released.

This function can be used as the protection of abnormal operations.

The CSS pin input voltage should be set  $V_{CSS(1)} = 8.6$  V (max.) or more and less than the absolute maximum ratings 12 V.

Since the sink current flows from the CSS pin in the overcurrent operation (refer to Section 8.10), the current supply ability of the external circuit should be set more than the CSS pin sink current (about 100 mA).

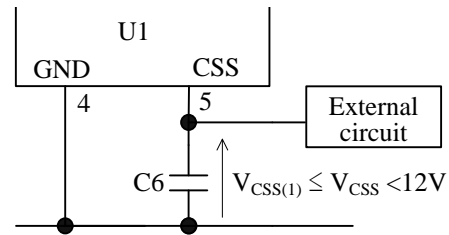


Figure 8-27. CSS pin peripheral circuit example

## 8.10 Overcurrent Protection (OCP)

When Overcurrent Protection (OCP) is activated, the output power is limited by detecting the drain current of the power MOSFET at pulse-by-pulse.

The overcurrent is detected by the OC pin or the RC pin. Figure 8-28 shows the peripheral circuit of the OC pin and the RC pin.

C11 is the bypass capacitor. Since C11 is smaller than  $C_i$ , the detection current of  $R_{OCP}$  becomes low. Thus, the  $R_{OCP}$  can reduce loss and be small resistor.

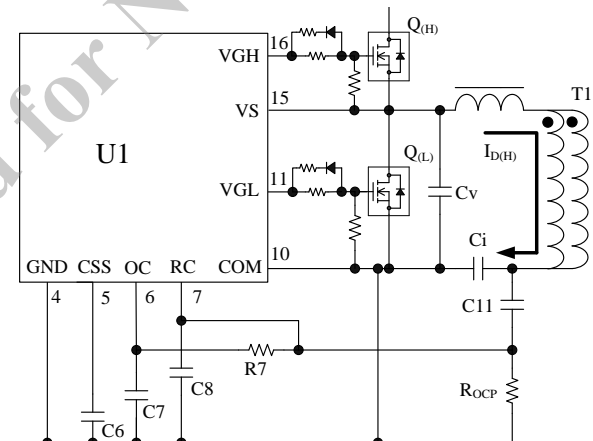


Figure 8-28. The Peripheral Circuit of OC Pin and RC Pin

Since the accurate value of the resonant current cannot be calculated easy from the condition of the resonant power supply including input voltage and output voltage, the value of  $R_{OCP}$ , C11, R7 and C7 should be adjusted based on actual operation in the application. R7 and C7 are the filter of the OC pin.

The value of  $R_{OCP}$ , C11, R7 and C7 are set as follows:

- C11 and  $R_{OCP}$   
C11 is 100pF to 330pF (around 1 % of  $C_i$  value).  
 $R_{OCP}$  is around 100  $\Omega$ .  
Given the current of the high side power MOSFET at ON state as  $I_{D(H)}$ ,  $R_{OCP}$  is calculated Equation (17).  
The detection voltage of  $R_{OCP}$  is used the detection of the capacitive mode operation (refer to Section 8.7).  
Therefore, setting of  $R_{OCP}$  and C11 should be taken



account of both OCP and the capacitive mode operation.

$$R_{OCP} \doteq \frac{V_{OC(L)}}{I_{D(H)} \times \left( \frac{C11}{C11 + C_i} \right)} \quad (17)$$

- R7 and C7 are for high frequency noise reduction.  
R7 is 100 Ω to 470 Ω. C7 is 100 pF to 1000 pF.

Table 8-1 shows the overcurrent detection voltage of the OC pin and the RC pin, and the sink current of CSS pin. There are three OCP operations as follows:

#### 1) Low Level OCP Detection

When the OC pin voltage becomes  $V_{OC(L)}$  or more, C6 connected to the CSS pin is discharged by the sink current  $I_{CSS(L)}$ . As a result, the oscillation frequency increases, the output power is limited.

If the OC pin voltage decreases less than  $V_{OC(L)}$  during discharge of C6, the IC stops discharge of C6.

#### 2) High Level OCP Detection

When the OC pin voltage becomes  $V_{OC(H)}$  or more, C6 is discharged by the sink current  $I_{CSS(H)}$ . Since  $I_{CSS(H)}$  is eleven times of  $I_{CSS(L)}$ , the oscillation frequency increases at high speed, the output power is limited quickly. If the OC pin voltage decreases less than  $V_{OC(H)}$  during discharge of C6, the IC becomes the Low Level OCP Detection.

#### 3) High Speed OCP Detection

In case the large current flows as output is shorted, this protection is activated. When the OC pin voltage or the RC pin voltage becomes as follows, the switching states of the power MOSFET is inverted.

OC pin voltage is more than  $V_{OC(S)}$  or RC pin voltage is more than  $|V_{RC(S)}|$ .

At same time, C6 is discharged by the sink current  $I_{CSS(S)}$ . As a result, the oscillation frequency increases at high speed, the output power is limited quickly. If the OC pin voltage decreases less than  $V_{OC(S)}$  or the RC pin voltage becomes within  $|V_{RC(S)}|$  due to reducing the output power, the IC becomes the High Speed OCP Detection and the Low Level OCP Detection.

Table 8-1. Overcurrent Detection Voltage and Sink Current of CSS Pin

OCP	Pins	Detection Voltage	CSS Pin Sink Current
Low	OC	$V_{OC(L)} = 1.52 \text{ V}$	$I_{CSS(L)} = 1.8 \text{ mA}$
High	OC	$V_{OC(H)} = 1.83 \text{ V}$	$I_{CSS(H)} = 20.0 \text{ mA}$
High Speed	OC	$V_{OC(S)} = 2.35 \text{ V}$	$I_{CSS(S)} = 18.3 \text{ mA}$
	RC	$V_{RC(S)} = 2.35 \text{ V}, -2.35 \text{ V}$	

## 8.11 Overload Protection (OLP)

Figure 8-29 shows the FB pin peripheral circuit, Figure 8-30 shows the FB pin waveform at Overload Protection (OLP) operation.

When the output power becomes overload state that the drain current is limited by Overcurrent Protection (OCP) operation, the oscillation frequency increases. When the oscillation frequency increases, the output voltage decreases and the current of the secondary photo-coupler becomes zero. Thus, the feedback current flowing through the photo-coupler connected the FB pin becomes zero. As a result, C4 is charged by the FB Pin Source Current  $I_{FB} = -25.5 \mu\text{A}$ , and the FB pin voltage increases. If the FB pin voltage increases to the FB Pin Threshold Voltage  $V_{FB} = 7.05 \text{ V}$ , the IC stops switching operation in the latch mode. When the VCC pin voltage is decreased to  $V_{CC(LA\_OFF)} = 8.2 \text{ V}$  or less or the VSEN pin voltage is decreased to  $V_{SEN(OFF)} = 1.16 \text{ V}$  or less, the latch mode is released.

The stresses of the power MOSFET and the secondary side rectifier diode are reduced by OLP.

Given the time that until the FB pin voltage reaches to  $V_{FB}$  as the OLP delay time,  $t_{DLY}$  (refer to Figure 8-30).  $t_{DLY}$  is calculated Equation (18).

If R5 is 47 kΩ and C4 is 4.7 μF,  $t_{DLY}$  becomes about 0.5 s.

$$t_{DLY} \doteq \frac{(4.05 \text{ V} - R5 \times |I_{FB}|) \times C4}{|I_{FB}|} \quad (18)$$

Where,  $I_{FB}$  is the FB Pin Source Current  $-25.5 \mu\text{A}$ .

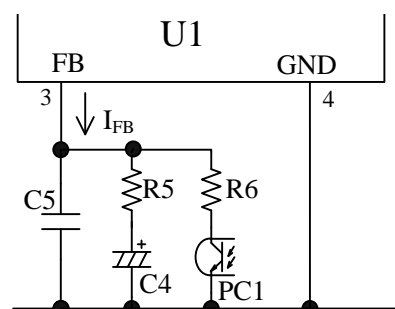


Figure 8-29. FB Pin Peripheral Circuit

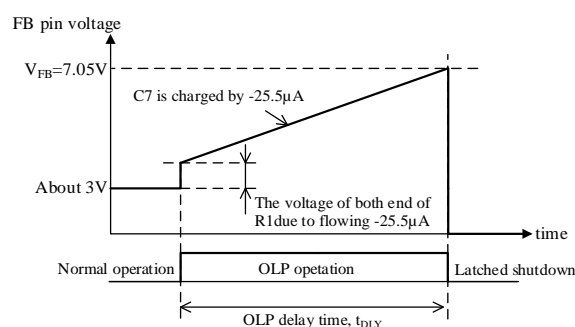


Figure 8-30. OLP Operation

## 8.12 Overvoltage Protection (OVP)

When the VCC pin voltage increases to the VCC Pin OVP Threshold Voltage  $V_{CC(OVP)} = 31.0\text{ V}$ , Overvoltage Protection (OVP) is activated and the IC stops switching operation in the latch mode. When the VCC pin voltage is decreased to  $V_{CC(LA\_OFF)} = 8.2\text{ V}$  or less or the VSEN pin voltage is decreased to  $V_{SEN(OFF)} = 1.16\text{ V}$  or less, the latch mode is released.

The VCC pin input voltage should be set absolute maximum ratings 35 V or less.

## 8.13 Thermal Shutdown (TSD)

When the junction temperature of the IC reach to the Thermal Shutdown Temperature  $T_{j(TSD)} = 150\text{ }^{\circ}\text{C}$  (min.), Thermal Shutdown (TSD) is activated and the IC stops switching operation in the latch mode. When the VCC pin voltage is decreased to  $V_{CC(LA\_OFF)} = 8.2\text{ V}$  or less or the VSEN pin voltage is decreased to  $V_{SEN(OFF)} = 1.16\text{ V}$  or less, the latch mode is released.

### • Gate Pin Peripheral Circuit

The VGH pin and the VGL pin are for the gate drive of an external power MOSFET. The source peak current of the VGH pin and the VGL pin are  $-515\text{ mA}$ , the sink peak current of these pins are  $685\text{ mA}$ .

In Figure 9-1,  $R_A$ ,  $R_B$  and  $D_S$  should be adjusted by the loss of the power MOSFET and the gate waveform (reduction of ringing caused by pattern layout, and others) and EMI noise.

$R_{GS}$  is for preventing malfunction caused by precipitous  $dv/dt$  when the power MOSFET turns off. The value of  $R_{GS}$  is about  $10\text{ k}\Omega$  to  $100\text{ k}\Omega$ .  $R_{GS}$  is connected to near the Gate pin and the Source pin.

When the gate resistances are adjusted, the gate waveforms should be checked that the dead time is ensured as shown in Figure 9-2.

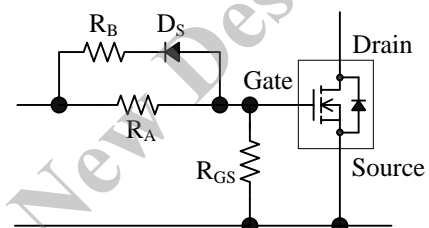


Figure 9-1. Peripheral Circuit of Power MOSFET Gate

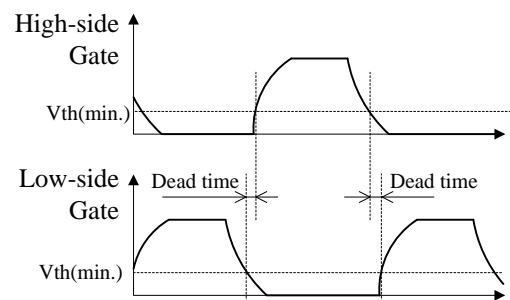


Figure 9-2. Dead Time Confirmation

## 9. Design Notes

### 9.1 External Components

Take care to use properly rated, including derating as necessary and proper type of components.

#### • Input and Output Electrolytic Capacitor

Apply proper derating to ripple current, voltage, and temperature rise. The electrolytic capacitor of high ripple current and low impedance types, designed for switch mode power supplies, is recommended to use.

#### • Resonant Transformer

The resonant power supply uses the leakage inductance of transformer. Therefore, in order to reduce the effect of the eddy current and the skin effect, the wire of transformer should be used a bundle of fine litz wires.

#### • Current Detection Resistor, $R_{OCP}$

Choose a type of low internal inductance because a high frequency switching current flows to  $R_{OCP}$ , and of properly allowable dissipation.

#### • Current Resonant Capacitor, $C_i$

Large resonant current flows through  $C_i$ .  $C_i$  should use the polypropylene film capacitor with low loss and high current capability. In addition,  $C_i$  must be considered its frequency characteristic since high frequency current flows.

## 9.2 PCB Trace Layout and Component Placement

Since the PCB circuit design and the component layout significantly affect the power supply operation, EMI noise, and power dissipation, the high frequency trace of PCB shown in Figure 9-3 should be designed low impedance by small loop and wide trace.

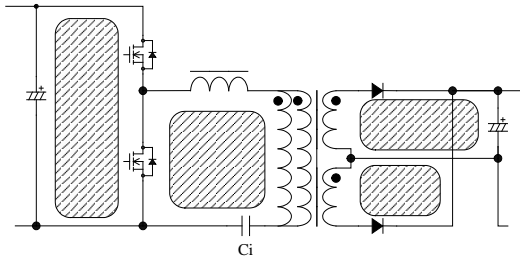


Figure 9-3. High Frequency Current Loops (hatched areas)

In addition, the PCB circuit design should be taken account as follows:

Figure 9-4 shows the circuit design example.

### 1) Main Circuit Trace Layout

This is the main trace containing switching currents, and thus it should be as wide trace and small loop as possible.

### 2) Control Ground Trace Layout

When large current flows into the control ground trace, the operation of IC might be affected by it. The control ground trace should be separate from the main circuit trace, and should be connected at a single point grounding as close to the GND pin as possible.

### 3) VCC Trace Layout

This is the trace for supplying power to the IC, and thus it should be as small loop as possible. If C3 and the IC are distant from each other, placing a film capacitor  $C_f$  (about 0.1  $\mu\text{F}$  to 1.0  $\mu\text{F}$ ) close to the VCC pin and the GND pin is recommended.

### 4) Peripheral Components for the IC Control

These components should be placed close to the IC, and be connected to the IC pin as short as possible.

### 5) Bootstrap Circuit Components

These components should be connected to the IC pin as short as possible, and the loop for these should be as small as possible.

### 6) Secondary side Rectifier Smoothing Circuit Trace Layout

This is the trace of the rectifier smoothing loop, carrying the switching current, and thus it should be as wide trace and small loop as possible.

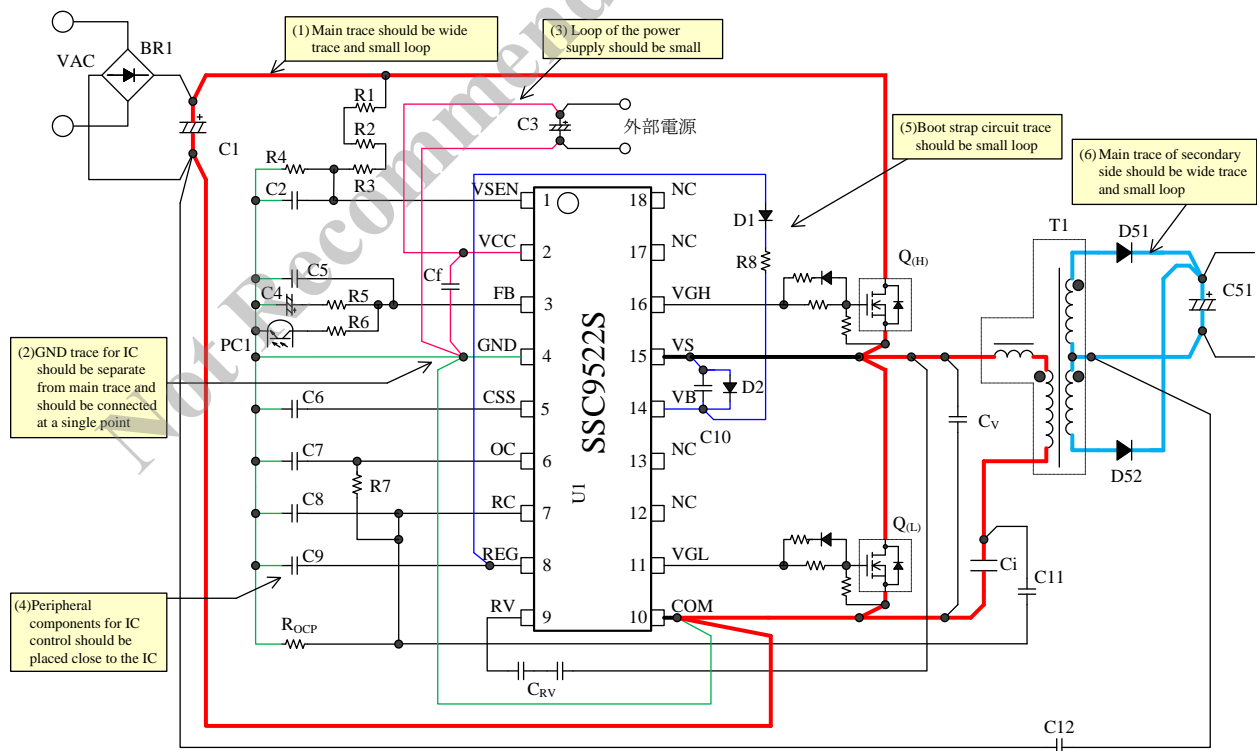


Figure 9-4. Peripheral Circuit Example Around the IC

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